



Japan EHS Committee Meeting Summary and Minutes

SEMICON Japan 2013

Friday, December 6, 2013 13:00-15:00 Makuhari Messe, Chiba, Japan

Next Committee Meeting Thursday, April 17, 2014, 11:00-13:00 SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Supika Mashiro (Tokyo Electron), Hidetoshi Sakura (Intel), Moray Crawford (Hatsuta Seisakusho)

SEMI Staff: Naoko Tejima (SEMI Japan)

Company	Last	First	Company	Last	First
Hatsuta Seisakusho	Crawford	Moray	Dainippon Screen Manufacturing	Nakatani	Eiji
Salus Engineering International	Evanston	Chris	Tokyo Electron	Nanbu	Mitsuju
SEMATECH	Ferrell	Jackie	Dainippon Screen Manufacturing	Nishiguchi	Naokatsu
Murata Machinery	Goto	Ikuo	Safe Techno	Nogawa	Kaoru
TÜV Rheinland Japan	Hamano	Yuji	Intel	Sakura	Hidetoshi
Daifuku	Hosaka	Yoshihiro	TÜV SÜD Japan	Sano	Tomokatsu
Tokyo Electron	Hoshi	George	Panasonic	Sugihara	Kenji
FM Approvals	Koga	Takuhiro	SEMI HQ	Baliga	Sanjay
Tokyo Electron	Mashiro	Supika	SEMI Japan	Tejima	Naoko

Tokyo Electron	Hoshi	George	Panasonic		Sugihara	Kenji
FM Approvals	Koga	Takuhiro	SEMI HQ		Baliga	Sanjay
Tokyo Electron	Mashiro	Supika	SEMI Japan		Tejima	Naoko
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Table 2 Leadership Changes						
None						
Table 3 Ballot Results						
None						
Table 4 Authorized Ballots						
None						
Table 5 Authorized Activities						
None						





Table 6 New Action Items

Item #	Assigned to	Details
EHS130418-05	S23 Revision TF	To submit the Line Item (1) ballot of Doc.#5513A for cycle 3 or 4.
EHS130418-08	Seismic Protection TF	To submit Doc.#5556 for cycle 4.(Delayed implementation preferred.)
IEHS131206-01	GHG Emission Characterization TF	To check the Device Manufacturers or SEMATECH whether S29 contents complies with EPA's GHG Report requirements.

1 Welcome, Reminders, and Introductions

Mashiro Supika, committee co-chair, called the meeting to order at 13:00. Self-introductions were made followed by the agenda review.

2 Technical Committee Award

Technical Committee Awards were given to the following members in appreciation of their outstanding efforts and leadership.

- Geroge Hoshi (Tokyo Electron) S23 Revision Task Force and GHG Emission Characterization Task Force activities
- Yoshihiro Hosaka (Daifuku) Seismic Protection Task Force activities

3 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

4 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on September 26, 2013.

Motion: To approve the minutes of the previous meeting, on condition of correcting the attendees. By / 2nd: Eiji Nakatani (Dainippon Screen Manufacturing) / Moray Crawford (Hatsuta Seisakusho)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_EHS_Previous_Mtg_Minutes_131206

5 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2013 Calendar of Events, Global Standards Meeting Schedule, Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, A&R Ballot Review Report, SEMICON Japan 2013 Information, SEMI Standards Meetings and Programs during SEMICON Japan 2013, SEMI Japan Standards Award and Contact Information.

Attachment: 02_SEMI_Staff_Report_131206

6 Liaison Reports

6.1 Japan Regional Standards Committee (JRSC)

Hidetoshi Sakura reported for the Japan Regional Standards Committee (JRSC) that there were no particular things should be reported.





6.2 Global Coordinating Subcommittee (GCS)

Hidetoshi Sakura reported for the Global Coordinating Subcommittee (GCS) that there were no activities between the previous committee meeting and today.

6.3 North America EHS Committee

6.3.1 North America EHS Committee Report

Chris Evanston reported for the North America EHS Committee. This report included Task Force and Leadership Changes, Organization Chart, Meeting Information, Publication information, Document Review Summary at NA Fall 2013 Meetings, Ballots to be Reviewed at NA Spring 2014 Meetings, New TFOFs and SNARFs, Subcommittees & Task Forces Updates, NA Standards Spring 2014 Meetings Schedule and Contact Information.

 Spika Mashiro asked who will be a GCS member in NA EHS Committee. Chris Evanston replied that he will get back to us after discussion.

Attachment: 03_NA_EHS_Report_December2013_131206

6.3.2 Proposal of Guideline for Handling of Energetics

Jackie Ferrell and Andy McIntyre (assisting through telephone), SEMATECH, presented "Energetics in Semiconductor Processing Best Known Methods and Standardization".

Attachment: 04 Energetics in Semiconductor Processing Best Known Methods and Standardization 131206

6.3.3 EHS Division Report

Sanjay Baliga reported for the EHS Division.

6.4 Europe EHS Committee

The Europe EHS Committee was disbanded at the previous at the Europe EHS Committee meeting and the former co-chairs joined the NA EHS Committee.

Attachment: 05_EU_EHS_Report_October2013_131206

6.5 Taiwan EHS Committee

No report was provided.

6.6 Korea EHS Working Group

No Report was provided.

7 Subcommittee & Task Force Reports

7.1 S23 Revision Task Force

George Hoshi reported on progress for the S23 Revision Task Force. Of note:

- TF is working for *Doc. #5513A*, *Line Item Revision to SEMI S23-0311*, *Guide for Conservation of Energy, Utilities and Materials Used by Semiconductor Manufacturing Equipment*, and the expansion of RI2 (Temperature Control Unit) is under preparation.
- Adding the section of the road map of the energy efficiency was proposed at the SEMI Standards NA Fall meeting, and TF will review about this proposal.

Action Item: S23 Revision Task Force to submit the Line Item (1) ballot of Doc.#5513A for cycle 3 or 4.

Attachment: 06_S23&GHG_TF_Report_131206





7.2 GHG Emission Characterization Task Force

George Hoshi reported for the GHG Emission Characterization Of note:

- TF is promoting the usage of S29, in cooperation with SEAJ.
- George Hoshi made a presentation of the S23 & S29 contents (Scope, Purpose, General Concept and so on) at SEMI EHS Standards workshop "EHS Challenges for 450mm" of December 4.
- EPA will mandate the Device Manufacturers to report about GHG from the next year, and it seems to be important that S29 contents can be used. TF should check whether it complies with EPA's GHG Report requirements.

Action Item: GHG Emission Characterization Task Force to check the Device Manufacturers or SEMATECH whether S29 contents complies with EPA's GHG Report requirements.

Attachment: 06_S23&GHG_TF_Report_131206

7.3 FPD System Safety Task Force

Naokatsu Nishiguchi reported for the FPD System Safety Task Force. The Task Force plans to start S26 revision activities from January, 2014. Its Scope is the non-ionizing radiation.

7.4 Seismic Protection Task Force

Eiji Nakatani reported on the progress for the Seismic Protection Task Force. Of note:

- TF has been working for Doc. #5556, Line Item Revisions to SEMI S2-0712, Environmental, Health, and Safety Guideline for Semiconductor Manufacturing Equipment Revisions Related to Section 19 Seismic Protection.
- TF will draft the document on target to submit it for Cycle 4, 2014.
- Chris Evanston asked whether the Task Force plans to use the delayed implementation format or not. And Supika
 Mashiro responded that using the delayed implementation format is a kind of an international agreement and it is
 highly recommended to use.

Action Item: Seismic Protection Task Force to submit Doc.#5556 for cycle 4.(Delayed implementation preferred.).

Attachment: 07_Seismic_Protection_TF_Report_131206

7.5 STEP Planning Working Group

Kenji Sugihara reported for the STEP Planning Working Group. Of note:

STEP/SEMI S2 "EHS Guideline for Semiconductor Manufacturing Equipment" was held on November 15 at SEMI
Japan Tokyo Office. 69 attendees attracted and with kind support of all speakers and committee co-chairs, it was
closed successfully.

Attachment: 08_STEP_Planning_WG_Report_131206

8 Old Business

8.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

Item #	Assigned to	Details
EHS130418-05	S23 Revision TF	To submit the Line Item (1) ballot of Doc.#5513A for cycle 3 or 4 Open
EHS130418-08	Seismic Protection TF	To submit Doc.#5556 for cycle 4.(Delayed implementation preferred.) Open





8.2 SEMI EHS Standards Workshop in conjunction with SEMICON Japan 2013

Hidtoshi Sakura reported for the SEMI EHS Standards workshop in conjunction with SEMICON Japan 2013. Of note:

SEMI EHS Standards workshop, "EHS Challenges for 450mm", was successfully finished on December 4. 49
attendees participated and the lively and fruitful discussion was held, thanks to the speakers and the project group
members.

Attachment: 09_SJ13_EHS_Program_Report_131206

9 New Business

None

10 Action Item Review

10.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

11 Next Meeting and Adjournment

The next meeting of the Japan EHS Committee is scheduled for Thursday, April 17, 2014, 11:00-13:00, at SEMI Japan, Tokyo, Japan.





Respectfully submitted by: Naoko Tejima Manager, Standards SEMI Japan

Phone: +81.3.3222.5804 Email: ntejima@semi.org

Minutes approved by:

Supika Mashiro (Tokyo Electron), Co-chair	Jan. **, 2014
Hidetoshi Sakura (Intel), Co-chair	Jan. 20, 2014
Moray Crawford (Hatsuta Seisakusho), Co-chair	Jan. 17, 2014

Table 8 Index of Available Attachments #1

#	Title
1	JA_EHS_Previous_Mtg_Minutes_131206
2	SEMI_Staff_Report_131206
3	NA_EHS_Report_December2013_131206
4	Energetics_in_Semiconductor_Processing_Best_Known_Methods_and_Standardization_131206
5	EU_EHS_Report_October2013_131206
6	S23&GHG_TF_Report_131206
7	Seismic_Protection_TF_Report_131206
8	STEP_Planning_WG_Report_131206
9	SJ13_EHS_Program_Report_131206

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.